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PATENT

Docket No.: NAUP0272USA

IN THE UNITED

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DEMARK OFFICE

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1. Assignor: Chih-Cheng Liu, De Yuan Wu
2. Assignee: UNITED MICROELECTRONICS CORP.
No.3, Li-Hsin Road 2,
Science-Based Industrial Park,
Hsin-Chu, Taiwan, R.O.C. 9/754350
3. Nature of Conveyance: Assignment of patent
4. Reference number: Application filed herewith.
5. Correspondence to: Winston Hsu
5F, No. 389, Fu-Ho Rd.,
234 YungHo City, Taipei Hsien,
Taiwan, R.O.C.
6. Number of applications affected by this recording: 1
Total fee: (1 x \$ 40) = \$ 40.00 Payment by check enclosed
Authorization is hereby given to charge the over payment to deposit account #500801
7. Execution date of the document to be recorded: 01/03/2001
8. Total number of pages including cover sheet: 3
9. I declare under penalty of perjury that to the best of my knowledge and belief, the information contained on this cover sheet is true and correct, and that any copy submitted herewith is a true and correct copy of the original document.

Date: 1/4/2001

Winston Hsu

Winston Hsu
U.S. Patent Agent
Reg. No.: 41,526

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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNORS (Inventors):

Name: Chih-Cheng Liu Nationality: R.O.C.

Address: No.9-1, Lane 153, Han-Sheng W. Rd., Pan-Chiao City, Taipei Hsien, R.O.C.

Name: De-Yuan Wu Nationality: R.O.C.

Address: No.14, Alley 10, Lane 452, Pao-Shan Rd., Hsin-Chu City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **UNITED MICROELECTRONICS CORP.**
(hereinafter 'Assignee'), of (Assignee address)

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.

, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Method for Fabricating a buried vertical split gate memory device with high coupling ratio"

Which is found in :

- (a) _____ U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 1/3/2000 (Date of signing).

(Type name of inventor)

Signature of INVENTOR

Chih-Cheng Liu

Chih - cheng Liu

De-Yuan Wu

De - Yuan Wu